



Material Content Data Sheet



Sales Product Name		SPD04N60C3		Issued		25. September 2017		
MA#		MA001145732						
Package		PG-TO252-3-313		Weight*		318.87 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.279	1.03	1.03	10282	10282
leadframe	non noble metal	iron	7439-89-6	0.147	0.05		462	
	inorganic material	phosphorus	7723-14-0	0.044	0.01		139	
	non noble metal	copper	7440-50-8	147.096	46.13	46.19	461308	461909
wire	non noble metal	aluminium	7429-90-5	0.521	0.16	0.16	1633	1633
encapsulation	organic material	carbon black	1333-86-4	1.405	0.44		4405	
	plastics	epoxy resin	-	24.579	7.71		77083	
	inorganic material	silicondioxide	60676-86-0	114.470	35.90	44.05	358989	440477
leadfinish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11729	11729
plating	inorganic material	phosphorus	7723-14-0	0.003	0.00		11	
	non noble metal	nickel	7440-02-0	1.421	0.45	0.45	4455	4466
solder	noble metal	silver	7440-22-4	0.074	0.02		232	
	non noble metal	tin	7440-31-5	0.059	0.02		186	
	non noble metal	lead	7439-92-1	2.827	0.89	0.93	8866	9284
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		60	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.01	6.02	60142	60220
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com